CRMGGH0814A

N-Channel 85V, 15mΩ Typ. Power MOSFET

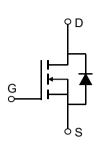
Description

Features

• 85V, 30A

 $R_{DS(ON)}$ Typ = 15m Ω @ V_{GS} = 10V Advanced Split Gate Trench Technology

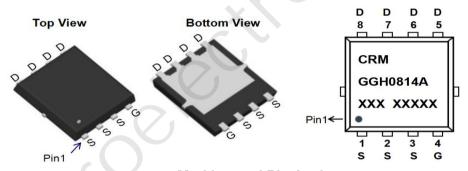
- Excellent R_{DS(ON)} and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!





Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMGGH0814A	CRMGGH0814A	PDFN5x6-8L	TAPING	13"	5000	50000

Absolute Maximum Ratings (@ $T_J = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		85	V
V _{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T _C = 25°C	30	Α
I _D	Continuous Diain Current	T _C = 100°C	18	Α
I _{DM}	Pulsed Drain Current (1)		120	Α
E _{AS}	Single Pulsed Avalanche Energy (2)		39	mJ
P_{D}	Power Dissipation	T _C = 25°C	31	W
$R_{ heta JC}$	Thermal Resistance, Junction to Case		4	°C/W
T_J,T_STG	Junction & Storage Temperature Range		-55 to 150	°C



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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Chara	acteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	85	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 85V, V_{GS} = 0V$	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				6)
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.4	3	3.6	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 10V, I_D = 20A$	-	15	19.5	mΩ
Dynamic	Characteristics					
C _{iss}	Input Capacitance		- (576	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 40V,$ f = 1MHz	-	197	-	pF
C_{rss}	Reverse Transfer Capacitance	1 – 1101112	X-\	10	-	pF
Q_g	Total Gate Charge		7 .	25	-	nC
Q_gs	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 40V, I_{D} = 10A$	U .	8	-	nC
Q_{gd}	Gate Drain("Miller") Charge	V _{DS} - 40V, I _D - 10A	-	7	-	nC
Switchin	g Characteristics					
t _{d(on)}	Turn-On DelayTime		-	12	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 40V$	-	8	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	I_D = 10A, R_{GEN} = 3Ω	-	20	-	ns
t_f	Turn-Off Fall Time		-	11	-	ns
Drain-So	urce Diode Characteristics and M	Max Ratings				
Is	Maximum Continuous Drain to Source Di	ode Forward Current	-	-	30	Α
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	120	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 20A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	1 - 404 - 11/24 - 4004/	-	33	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 10A$, di/dt = 100A/us	-	45	-	nC

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} E_{AS} condition: Starting T_J =25°C, V_{DD} =50V, V_G =10V, R_G =25ohm, L=0.5mH, I_{AS} =12.5A

^{3.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.



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Test Circuit

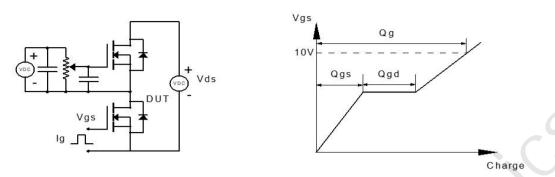


Figure 1: Gate Charge Test Circuit & Waveform

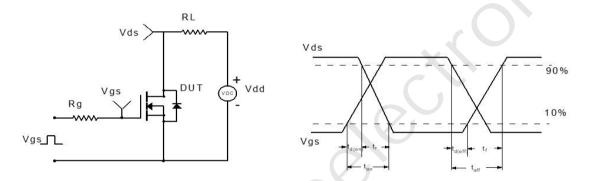


Figure 2: Resistive Switching Test Circuit & Waveform

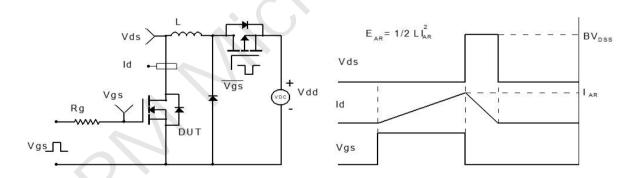


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

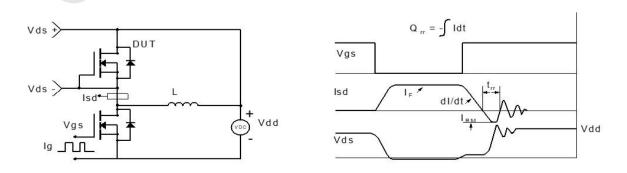
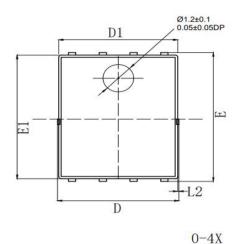


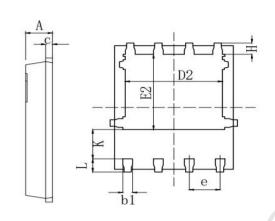
Figure 4: Diode Recovery Test Circuit & Waveform

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Package Mechanical Data(PDFN5x6-8L)





SYMBOL	MILLIMETER				
SIMBUL	MIN	NOM	MAX		
A	0.90	1.00	1.10		
b	0.25	0.30	0. 35		
b1	0.30	0.40	0.45		
c	0. 22	0. 25	0. 28		
D			5. 30		
D1	4. 90	5.05	5. 20		
D2	3. 90REF				
E	6.00	6. 15	6. 30		
E1	5. 70	5. 85	6.00		
E2	3. 50REF				
e	1. 10	1. 27	1.40		
Н	0. 51	0.61	0.71		
K	1. 10		-		
L	0. 51	0.61	0.71		
L2			0.10		
Φ	8°		12°		

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